

FIG. 1

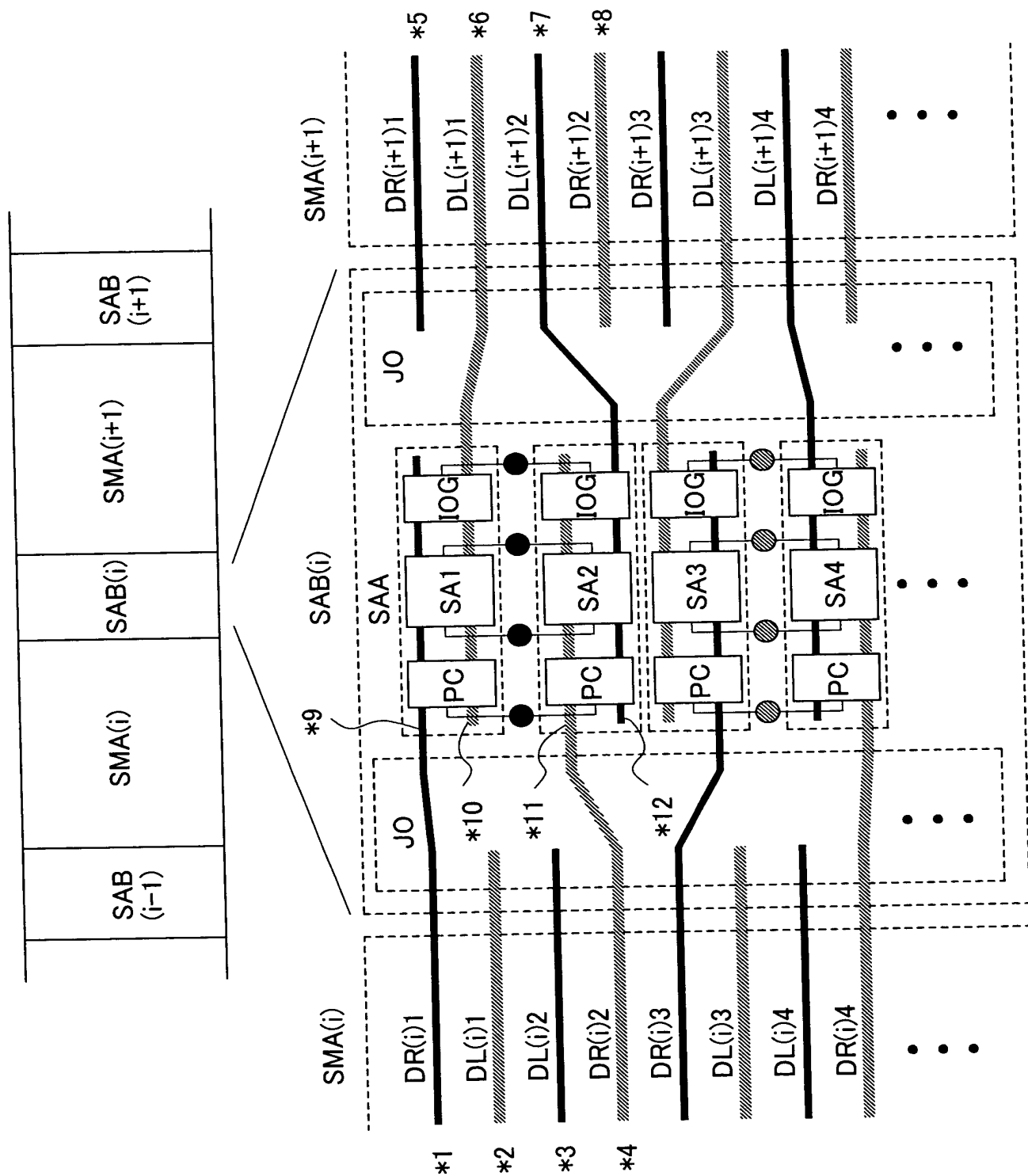


FIG. 2

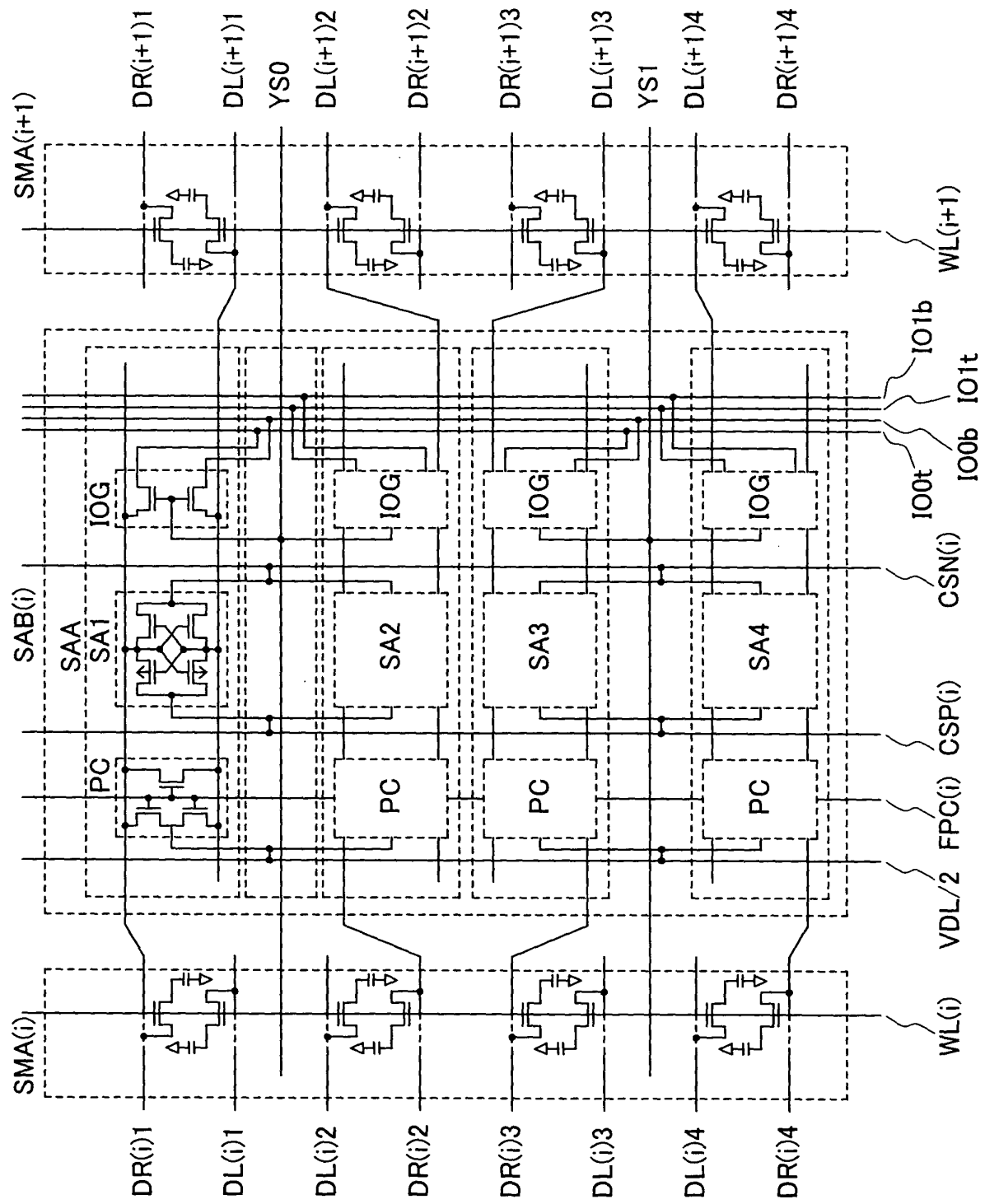
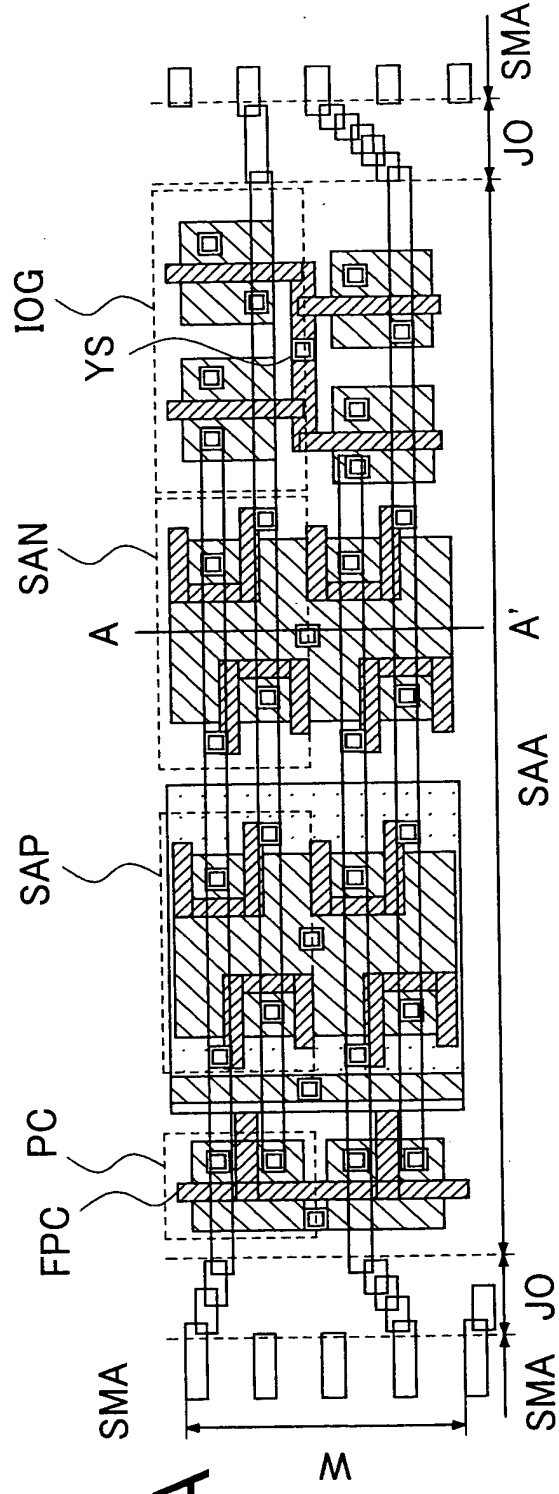


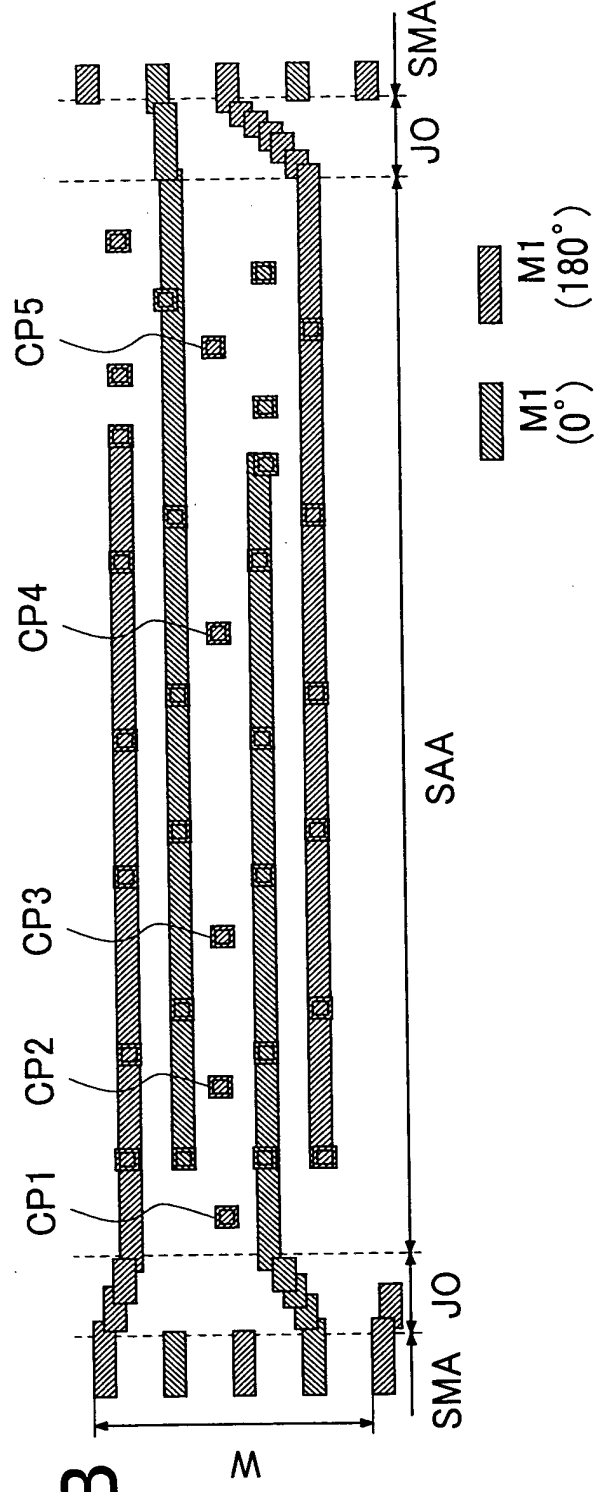
FIG. 3A



Legend for FIG. 3A:

- NWEL
- L
- FG
- M1
- CNT

FIG. 3B



Legend for FIG. 3B:

- M1 (0°)
- M1 (180°)

FIG. 4

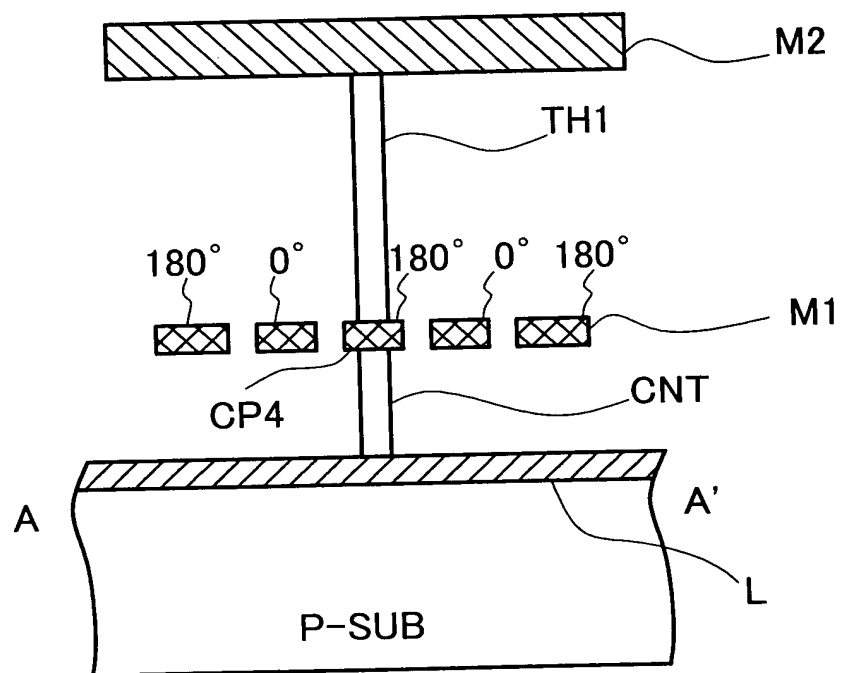


FIG. 5A

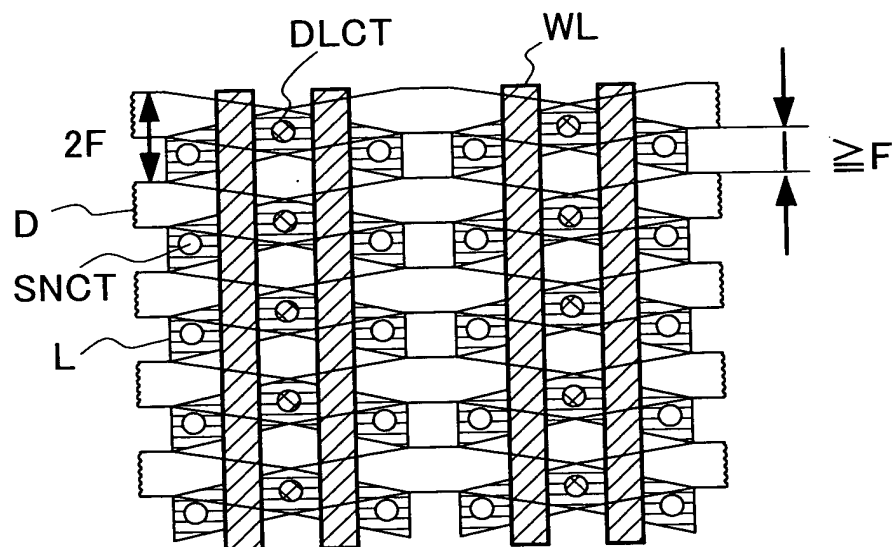


FIG. 5B

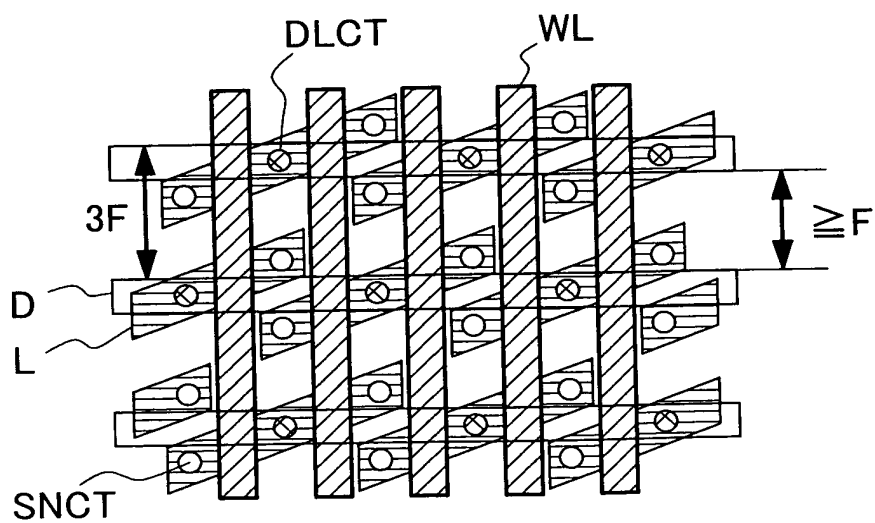


FIG. 6

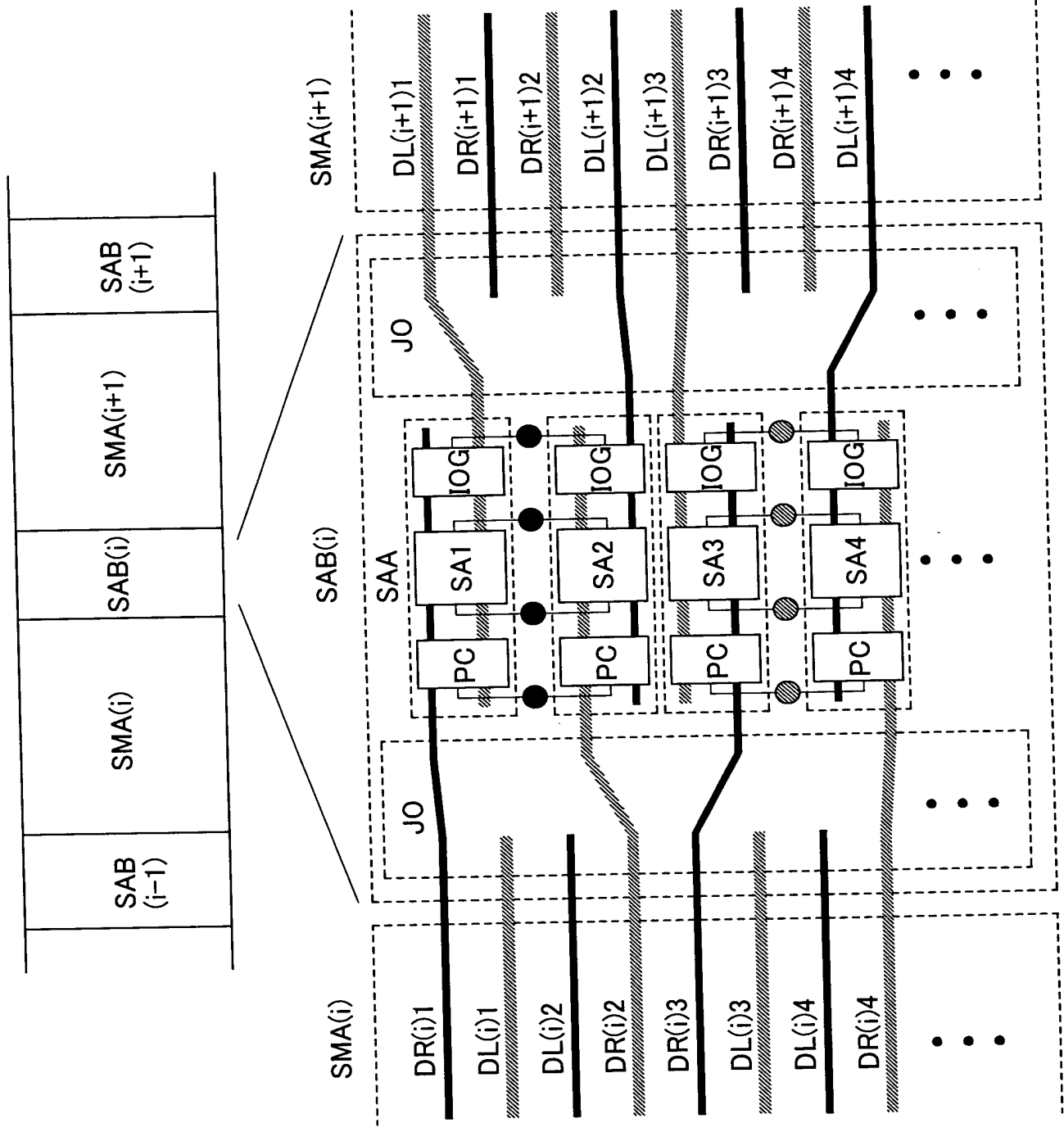


FIG. 7

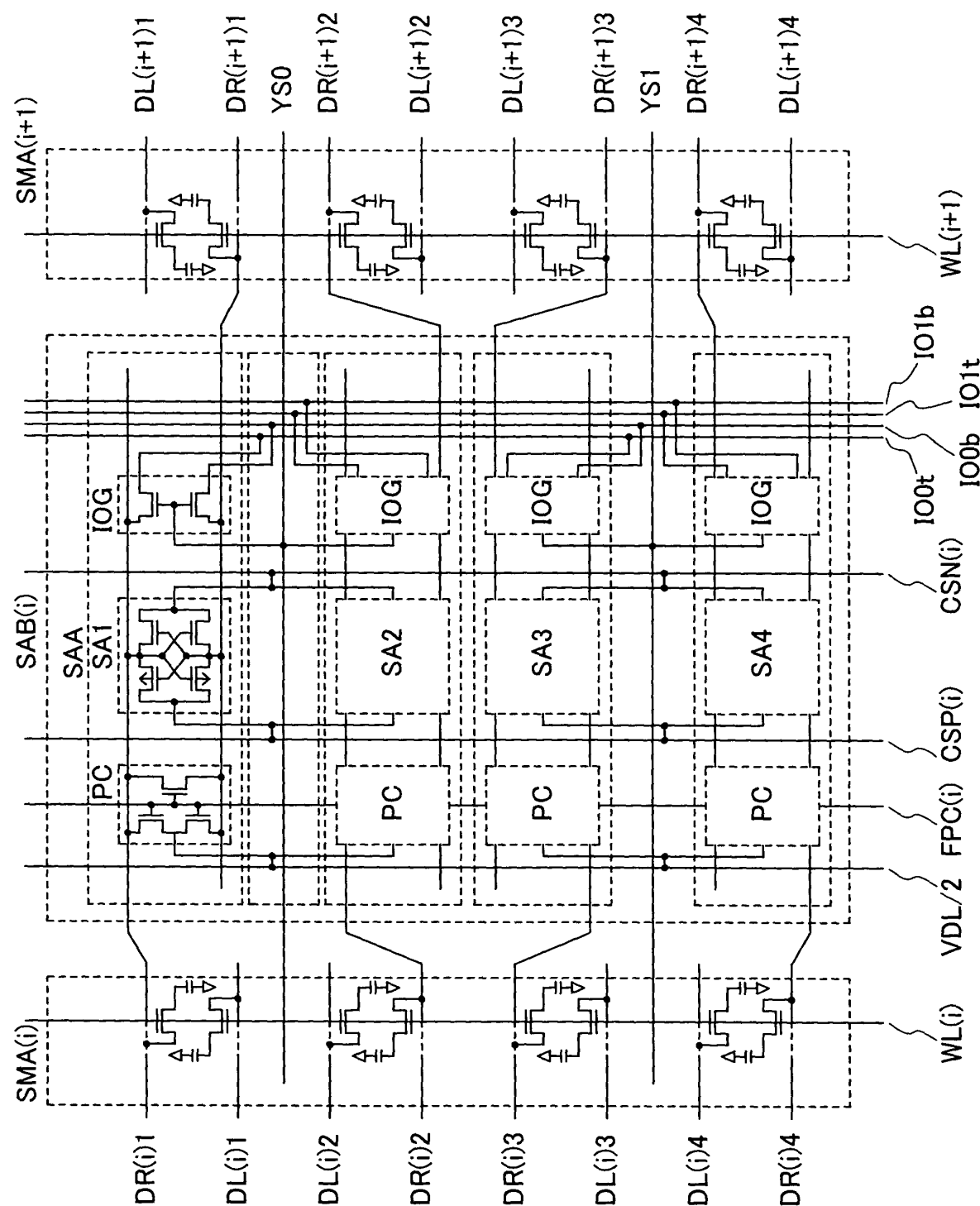


FIG. 8

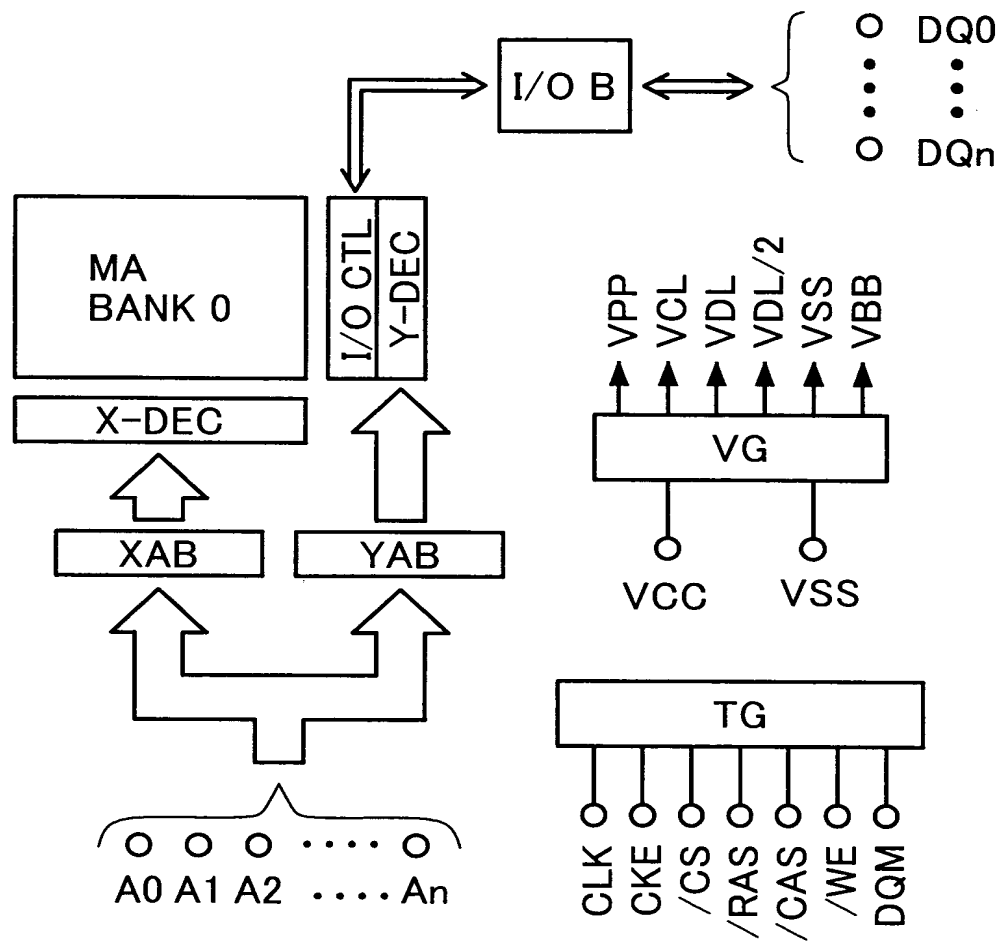


FIG. 9

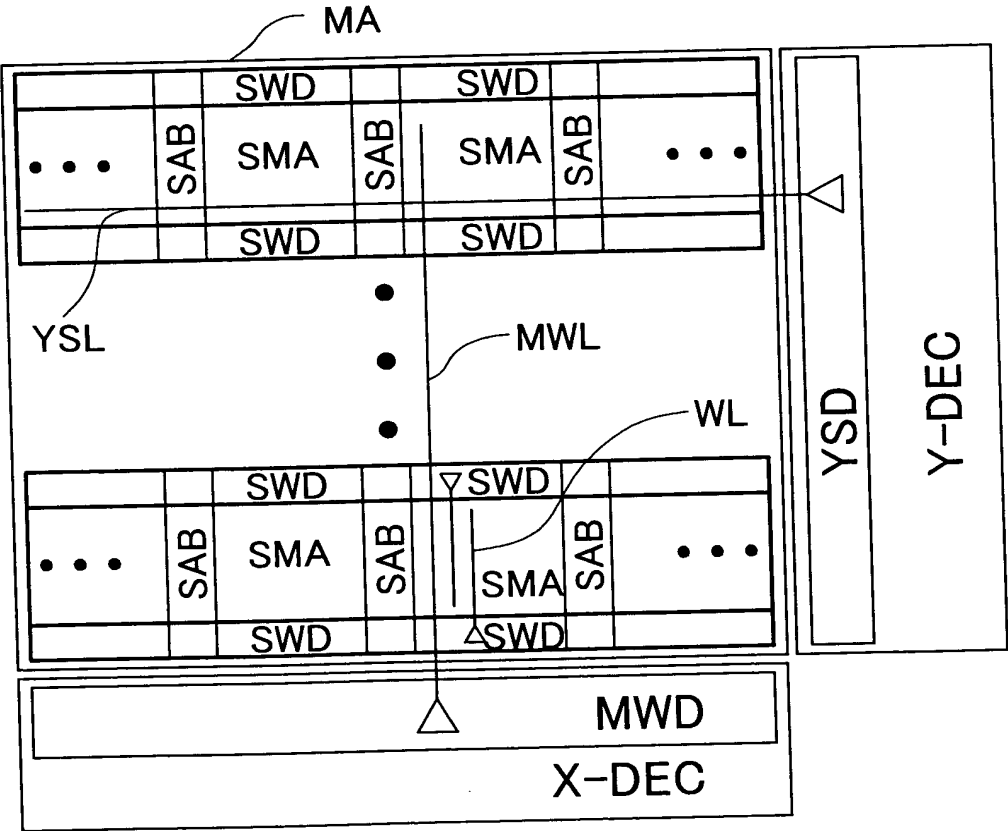


FIG. 10

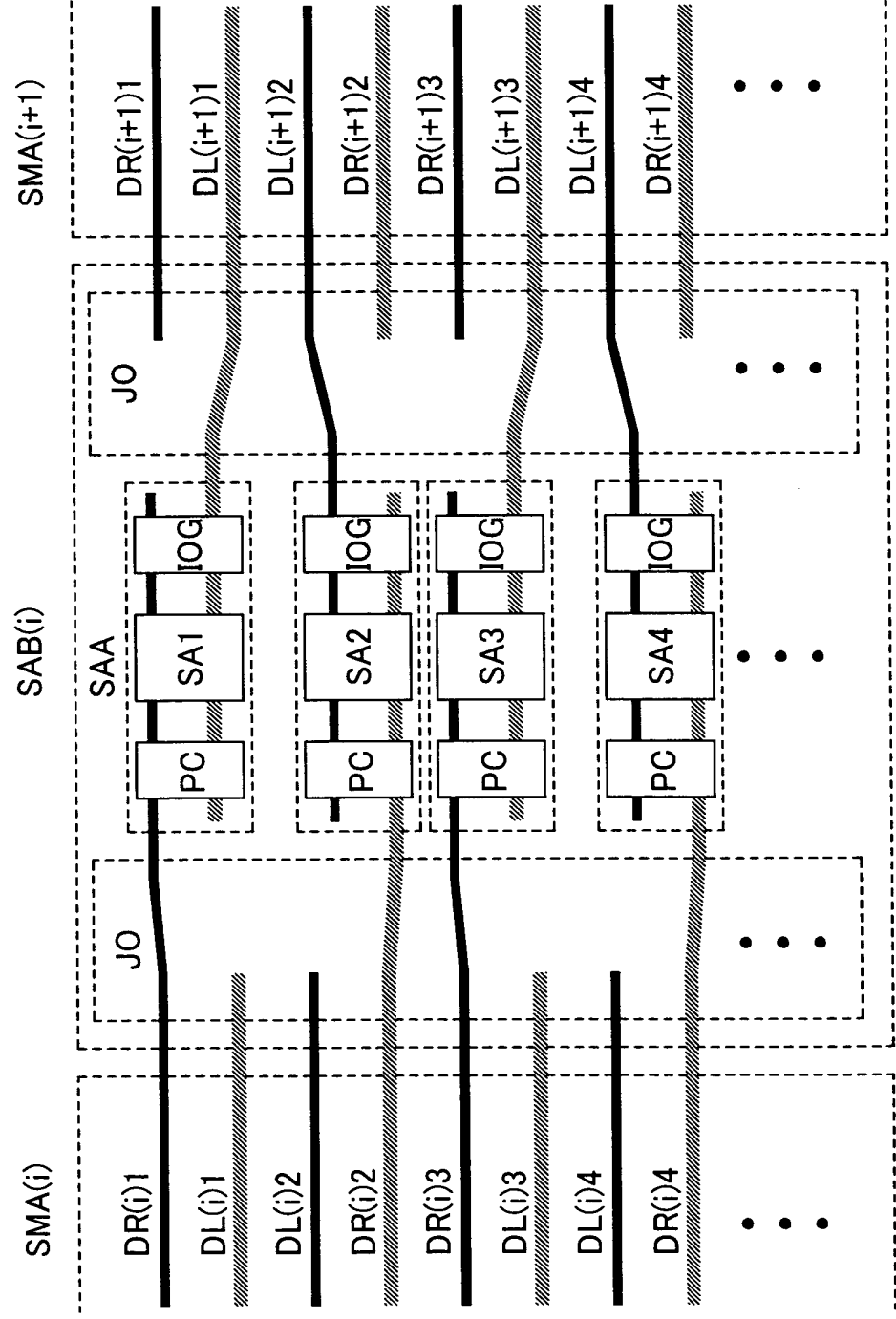


FIG. 11

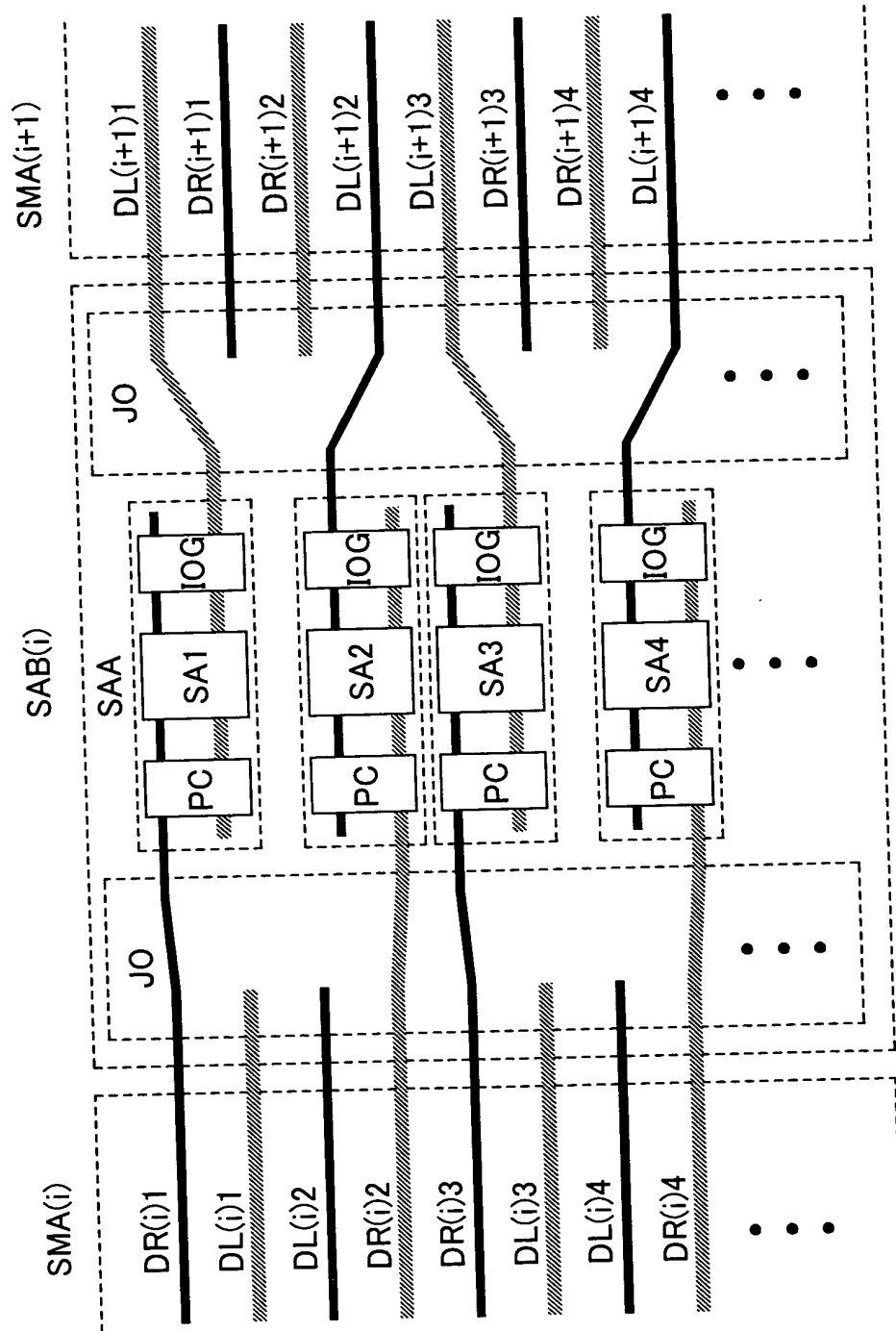


FIG. 12A

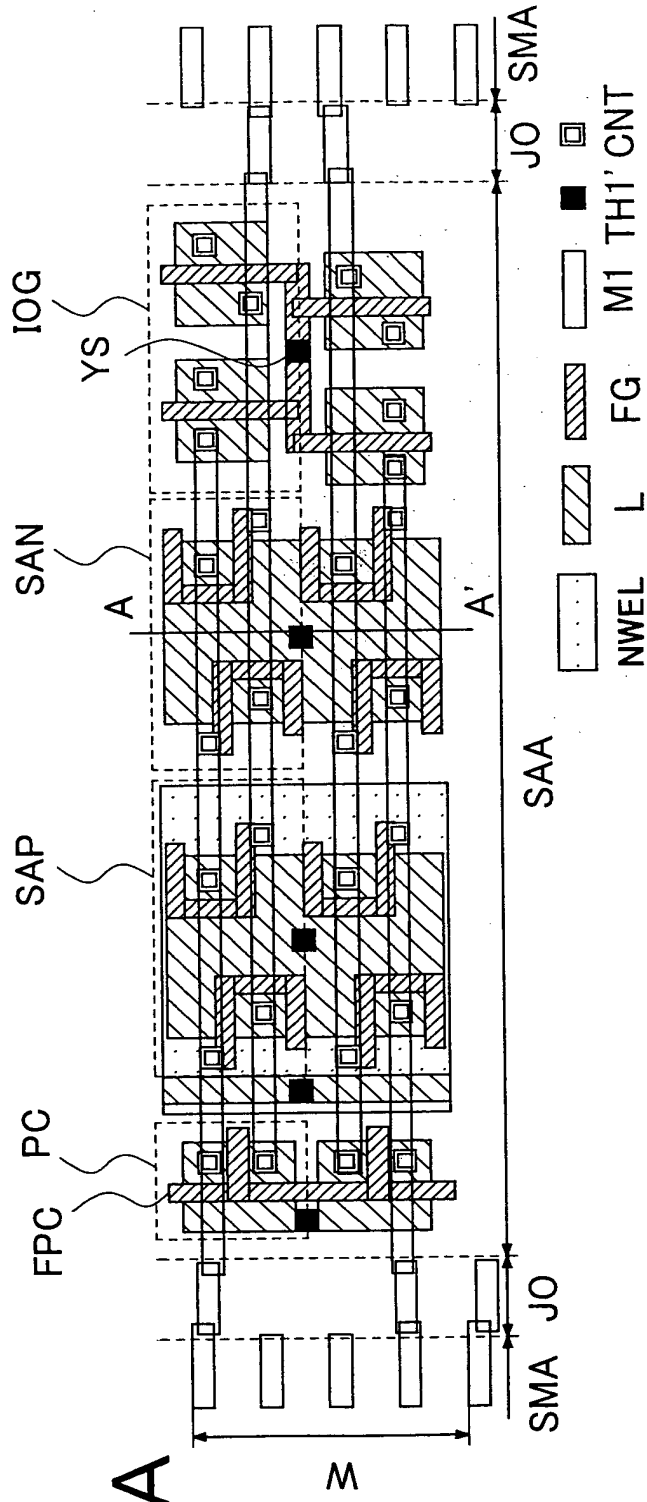


FIG. 12B

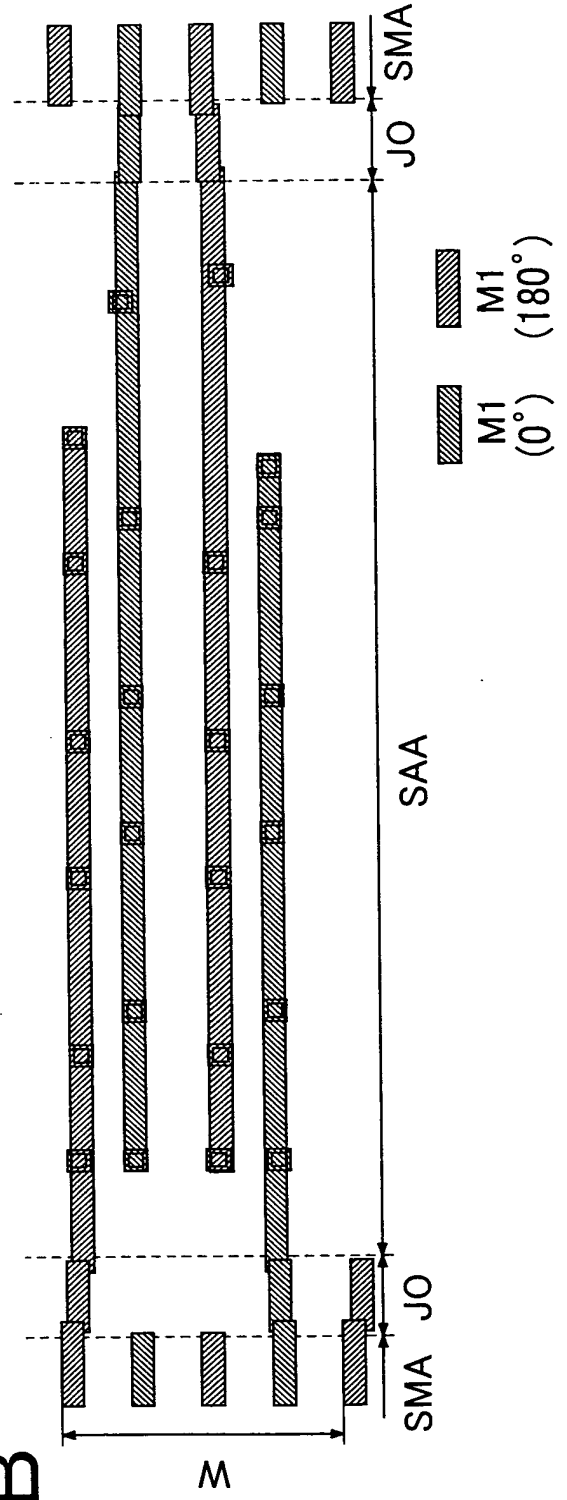


FIG. 13

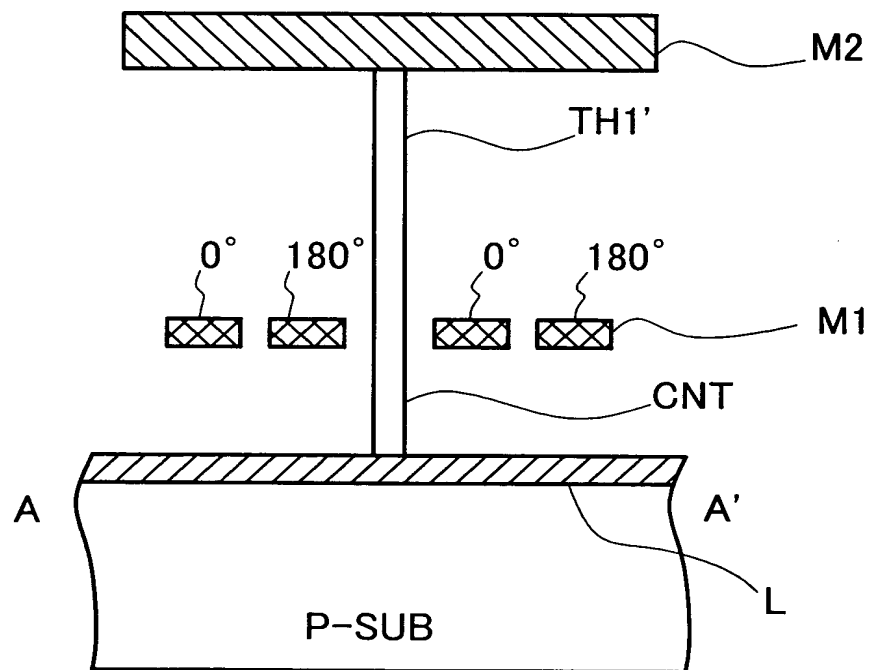


FIG. 14

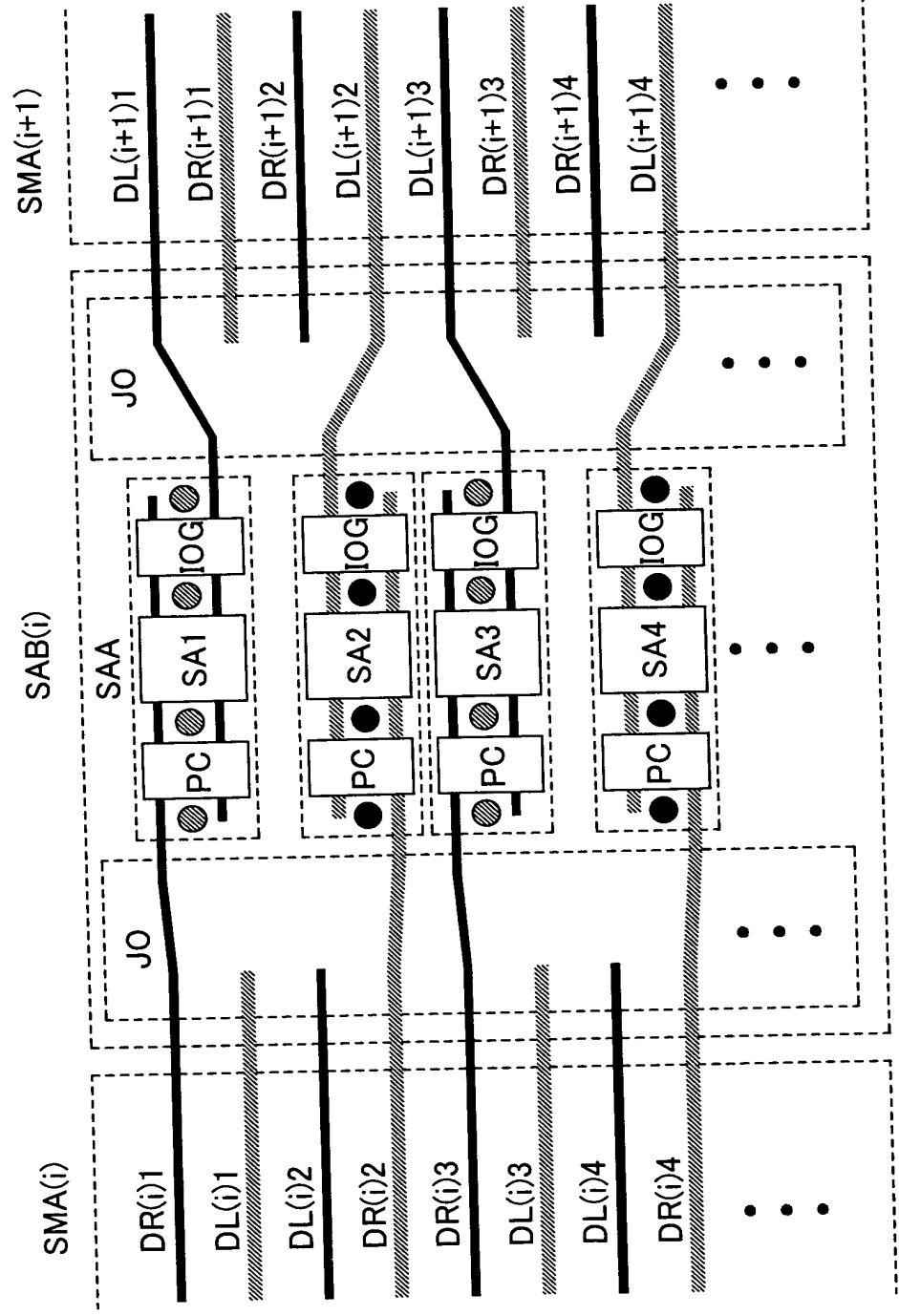


FIG. 15

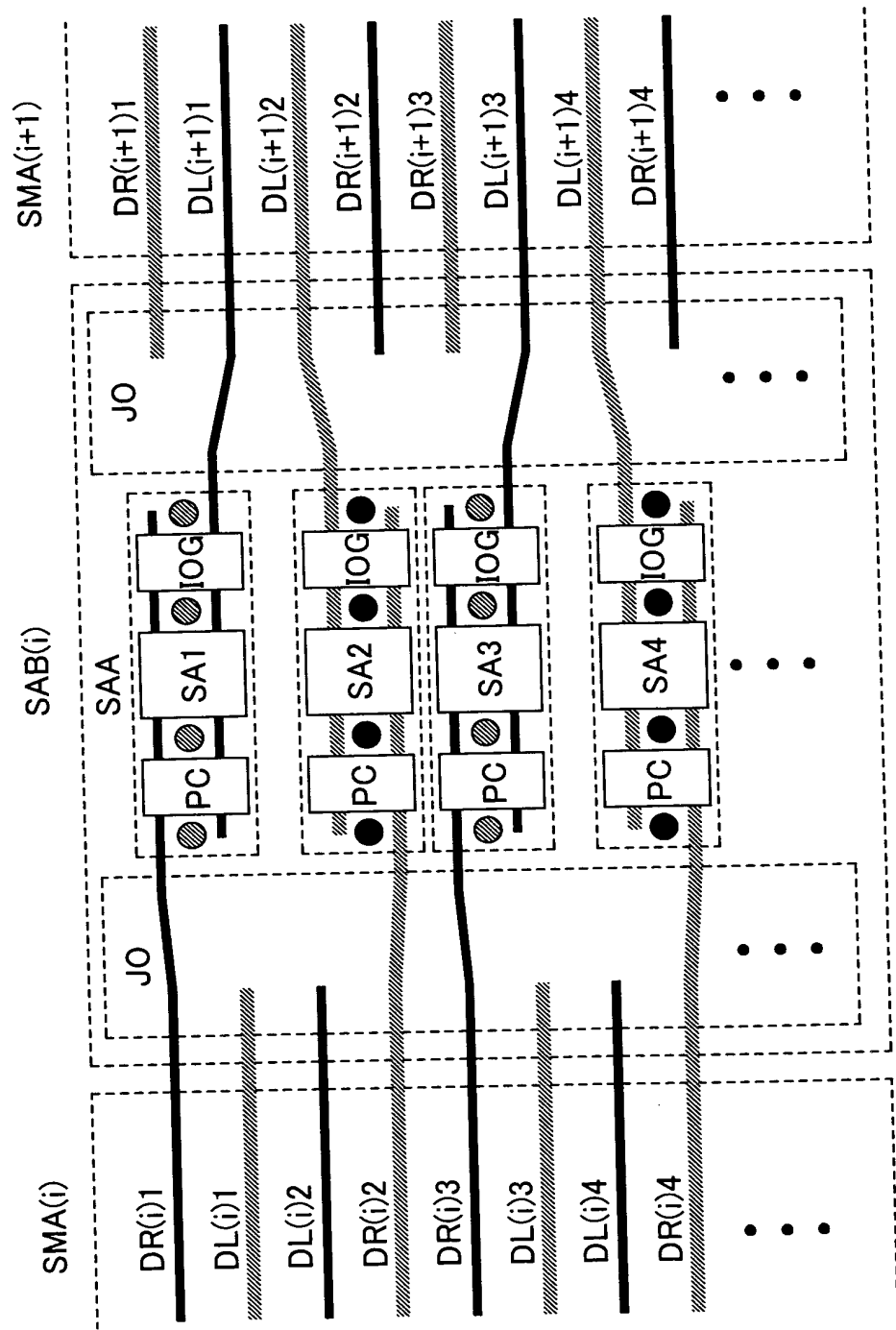


Figure 1 is a cross-sectional diagram of a multi-layer printed circuit board (PCB) assembly. The diagram shows various layers and components, including SMA connectors, IOG (Input/Output Grid), YS (Yield Surface), SAN (Signal Access Network), SAP (Signal Access Pad), PC (Printed Circuit), FPC (Flexible Printed Circuit), and SMA (Surface Mount Assembly). The assembly is divided into three main sections: SMA JO (Surface Mount Assembly Junction), SAA (Signal Access Area), and JO SMA (Junction Surface Mount Assembly). A legend on the right identifies the materials: NWEL (Nucleated Well), L (Laminate), FG (Fiberglass), M1 (Microvia 1), and CNT (Conductive Paste). The diagram also shows a cross-section line B-B' and a dimension M.

FIG. 17

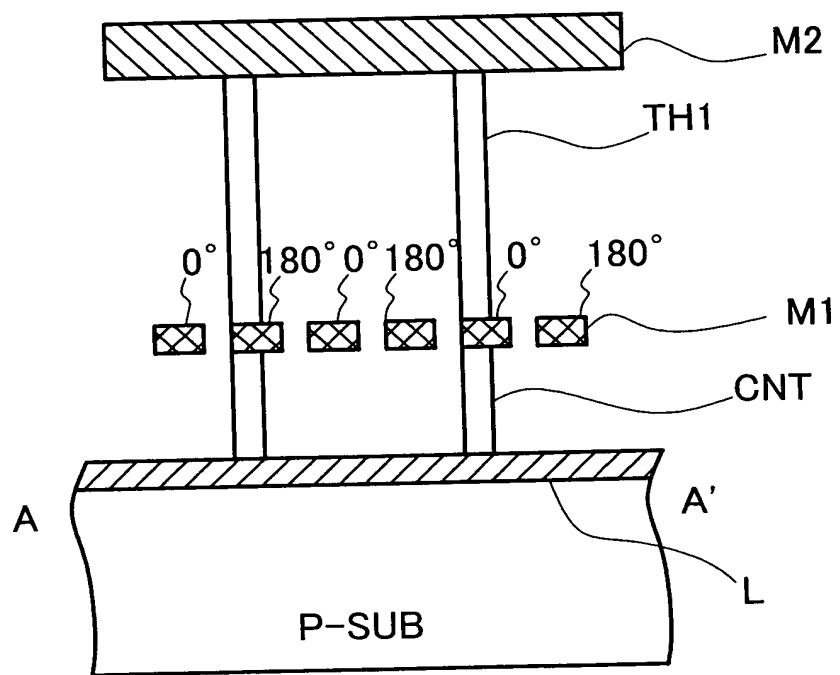


FIG. 18

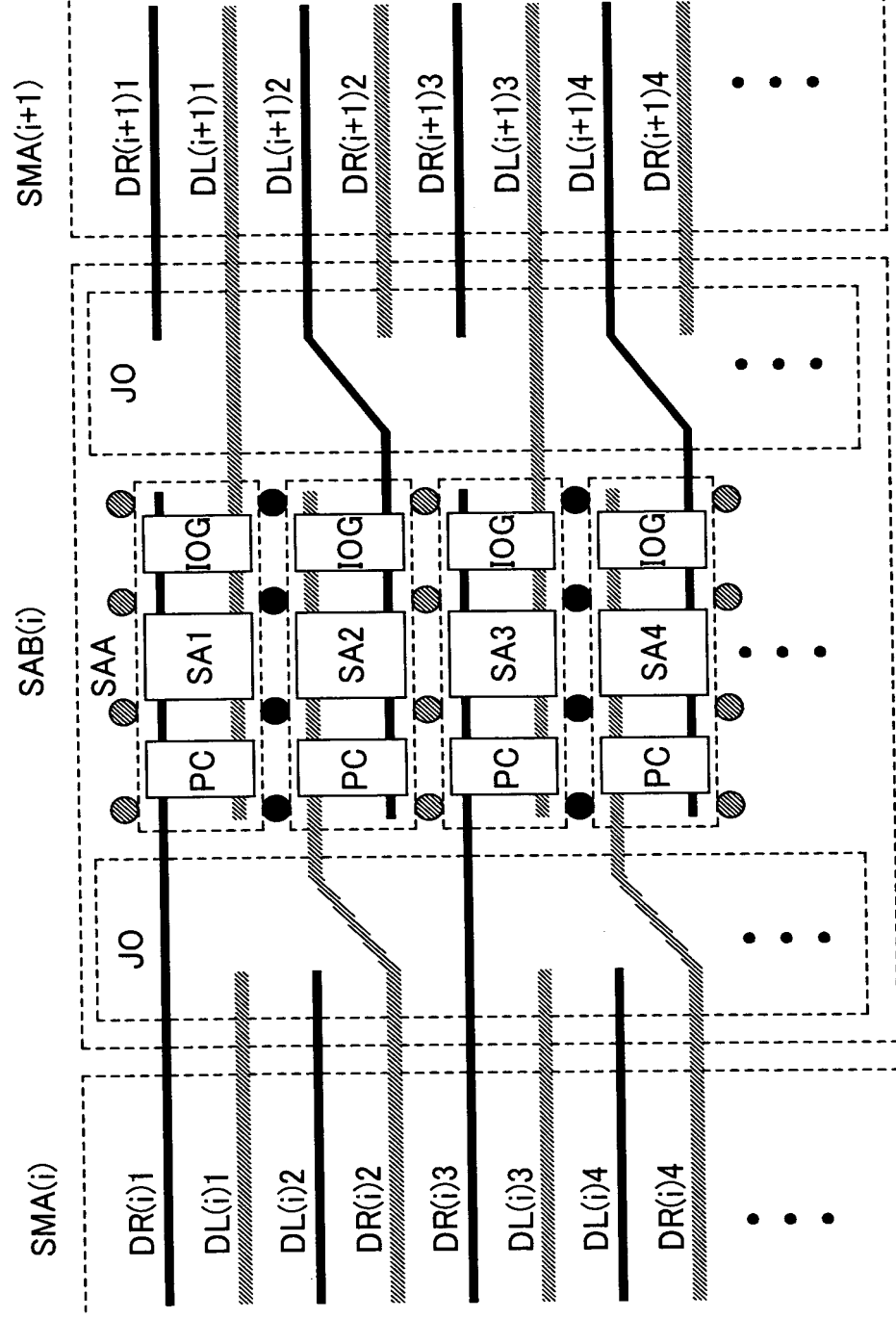


FIG. 19

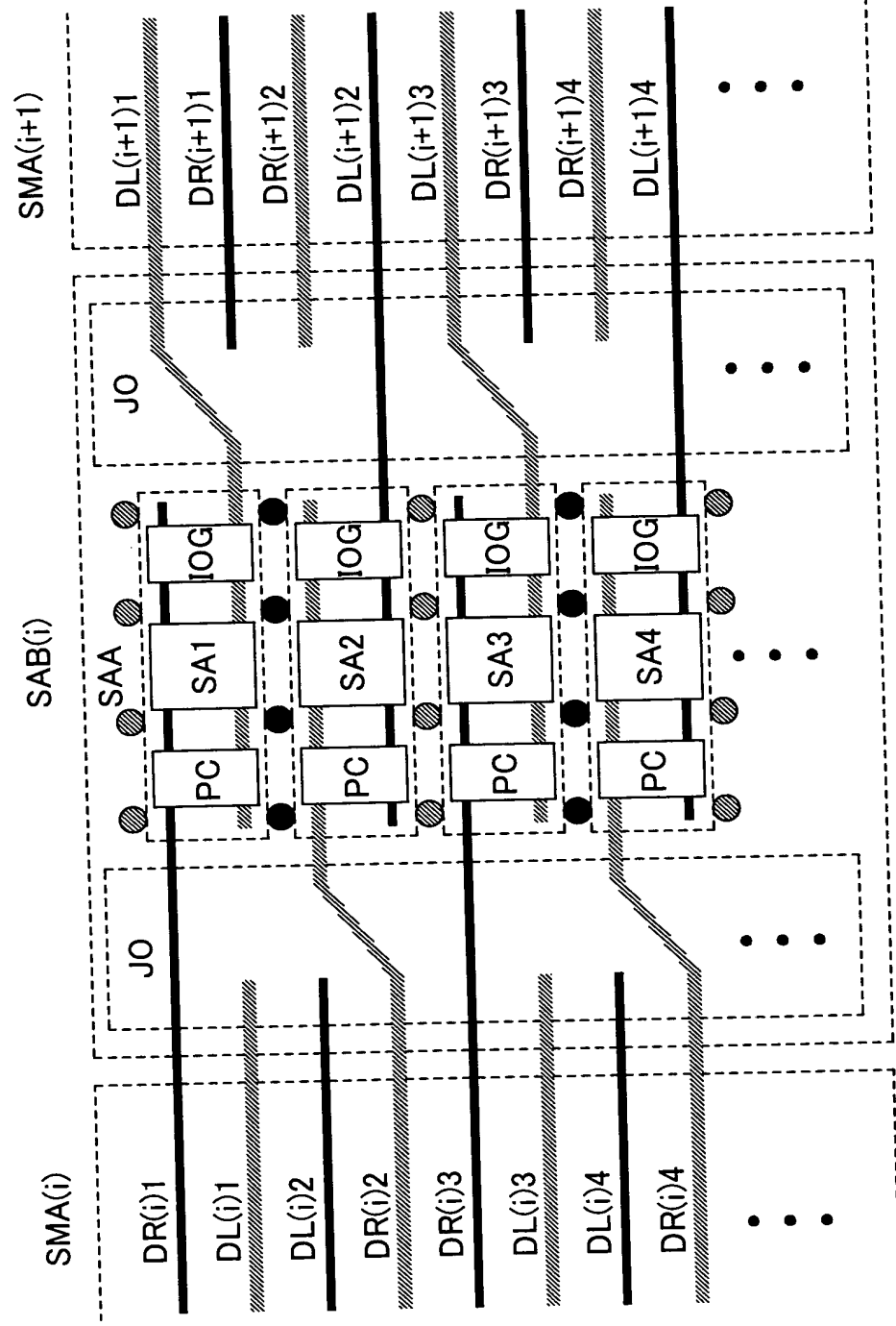


FIG. 20

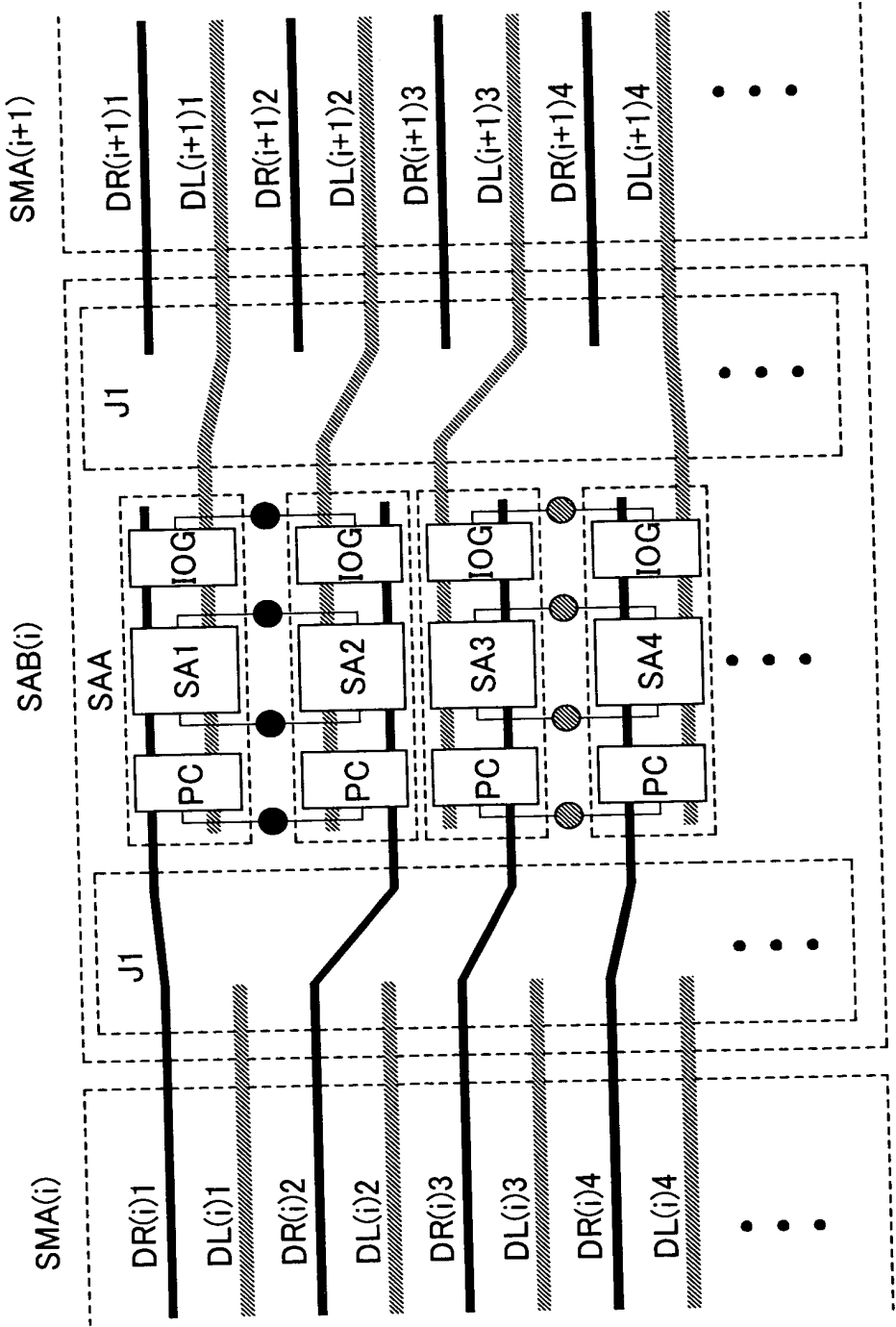


FIG. 21

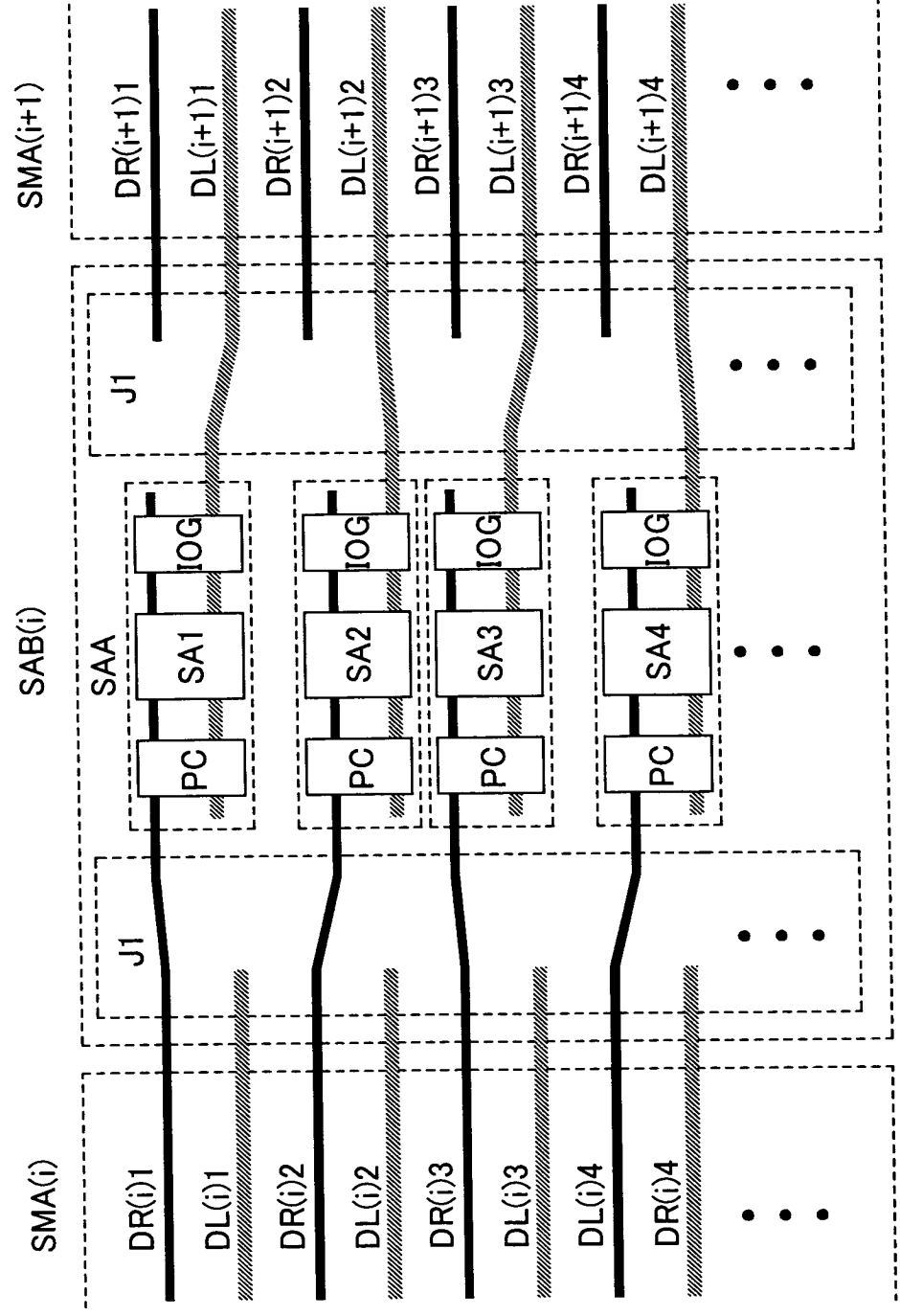


FIG. 22

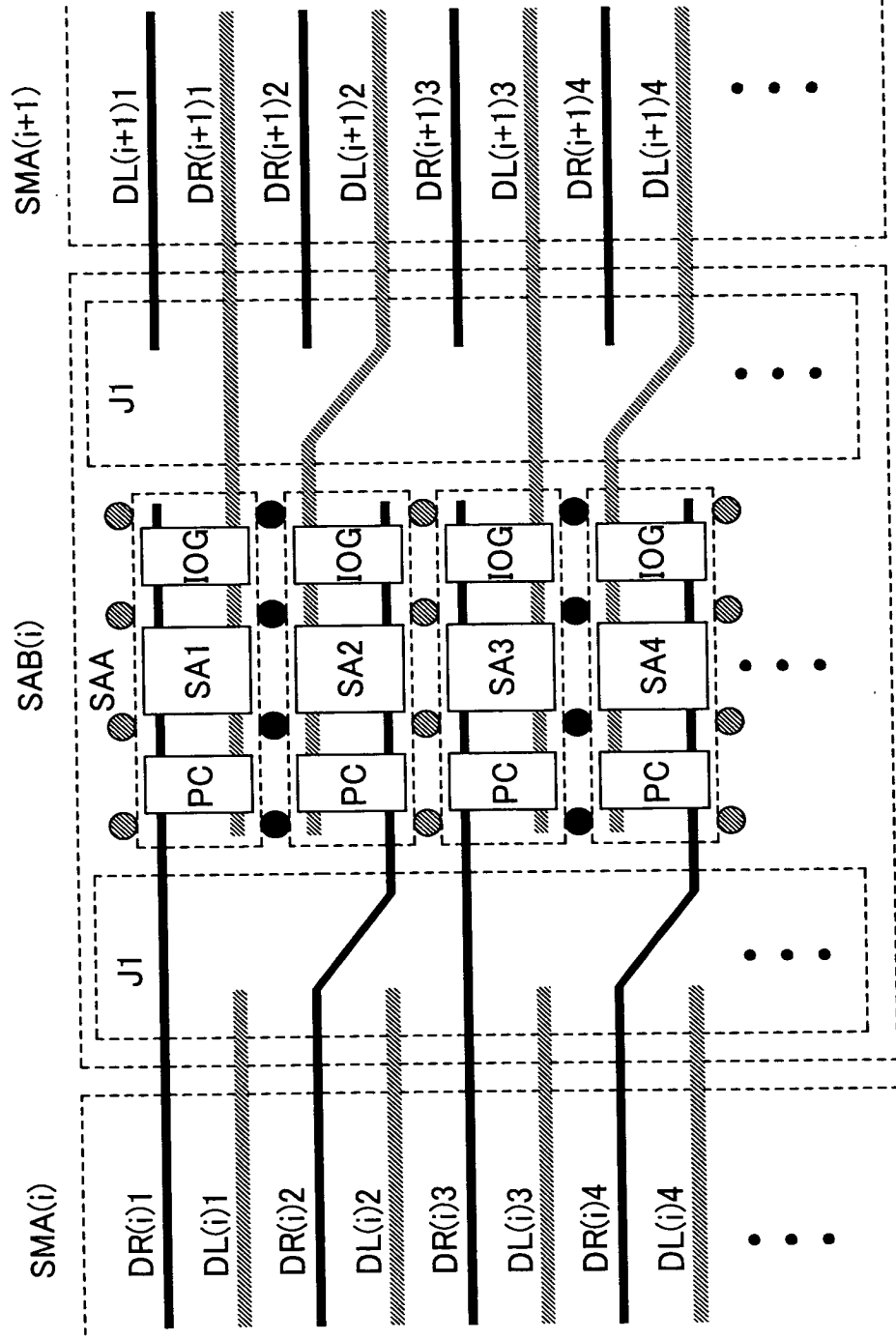


FIG. 23

